

CKC33C562KDGACTU

Aliases (CKC33C562KDGAC7800) KC-LINK Comm COG, Ceramic, 5600 pF, 10%, 1000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640



General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	false
AEC-Q200	No
Typical Component Weight	18 mg
Shelf Life	78 Weeks
MSL	1

	Specifications	
	Capacitance	5600 pF
	Measurement Condition	1 kHz 1.0Vrms
	Capacitance Tolerance	10%
	Voltage DC	1000 VDC
	Dielectric Withstanding Voltage	1200 VDC
	Temperature Range	-55/+150°C
	Temperature Coefficient	COG
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour
	Insulation Resistance	100 GOhms

Click here for the 3D model.

Dimensions	
Chip Size	3640
L	9.3mm +/-0.6mm
W	10.2mm +/-0.4mm
т	1.4mm +/-0.15mm
S	6.3mm MIN
В	1.27mm +/-0.4mm
D	1.2/11111 +/-0.4mm

Packaging SpecificationsPackagingT&R, 180mm, Plastic TapePackaging Quantity250

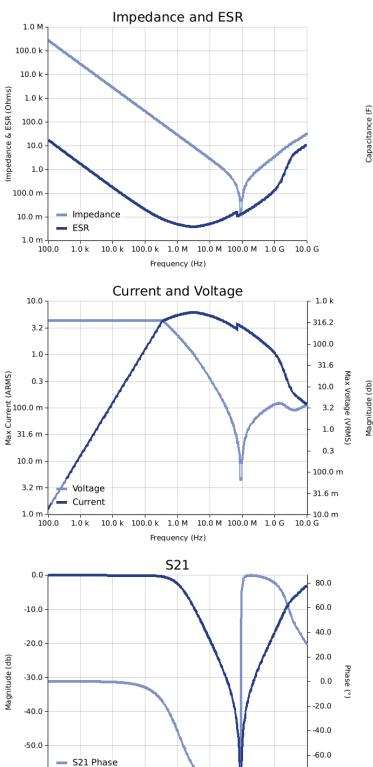
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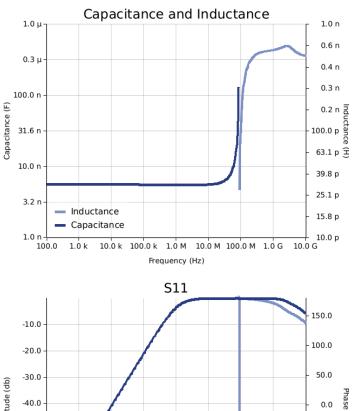
Simulations

For the complete simulation environment please visit K-SIM.



1.0 k 10.0 k 100.0 k 1.0 M 10.0 M 100.0 M 1.0 G 10.0 G

Frequency (Hz)



-40.0

-50.0

-60.0

-70.0

-80.0

-80.0

100.0

S11 Phase

1.0 k

S11 Magnitude

10.0 k 100.0 k 1.0 M

Frequency (Hz)

100.0

-60.0

- S21 Magnitude

0.0 °

-50.0

-100.0

-150.0

10.0 G

10.0 M 100.0 M 1.0 G



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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages are applied to reach previous the burger of the parts.
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.